

POWER MANAGEMENT

Features

- Input Voltage — 4.5V to 27V
- Output Voltage — Up to 50V
- Step-up (Boost) Controller
 - Ultra-Fast Transient Response (<100μs)
 - Programmable Switching Frequency
- Linear Current Sinks
 - 2 Strings, up to 240mA/String
 - Current Matching ±1%
 - Current Accuracy ±2%
- PWM Dimming
 - Direct PWM Dimming, 1000:1 at 1KHz
 - Input Dimming Frequency 100Hz-30kHz
- 5-Bits Analog Dimming
- I²C Interface
 - Fault Status — Open/Short LED, UVLO, OTP
- Protection Features
 - Open/Shorted LED(s) and adjustable OVP
 - Over-Temperature and UVLO Shutdown Protection
- 4mm X 4mm 20-pin QFN Package

Applications

- Ultrabooks™, All-in-One PCs, Monitors, Automotive-Display Backlighting
- Backlighting for Mid-Size Displays

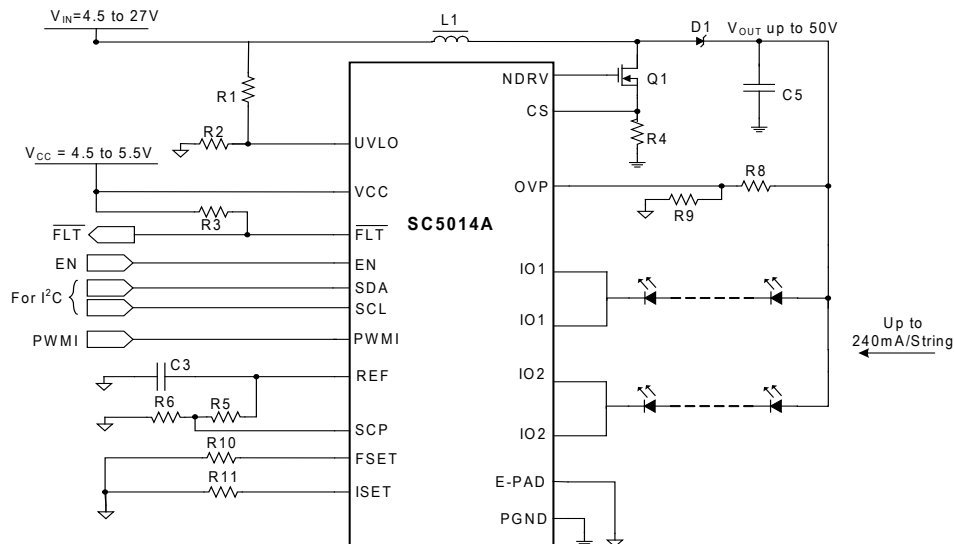
Description

The SC5014A is a 2-channel, highly integrated, high-efficiency step-up (boost) HB LED driver designed to reduce the thickness of mid-size LCD displays. It features a wide input voltage range (4.5V to 27V), direct PWM dimming, analog dimming, a flexible output configuration, an I²C interface, and numerous protection features.

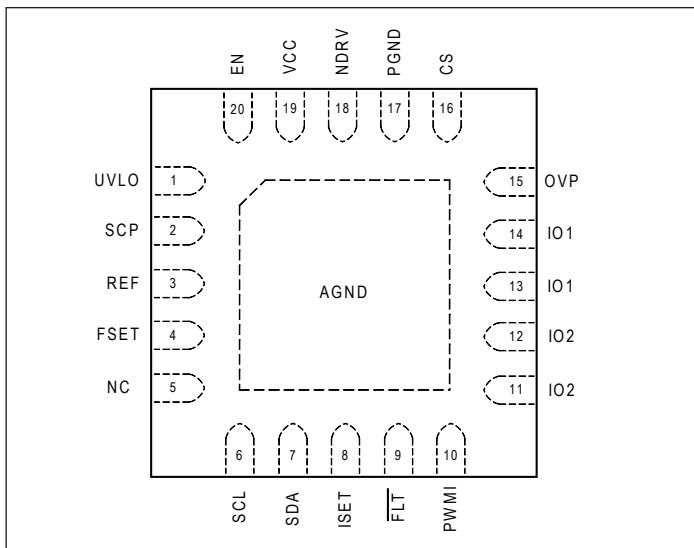
The SC5014A exhibits 2% to 4% higher efficiency when using the same size inductors as existing LED drivers. But, unlike existing devices, it can also operate with inductors that are up to 10x smaller without sacrificing efficiency. This part can also use very low-profile inductors (as small as 2.2μH, 1mm height), which allows LED drivers to be built directly into the LCD panel to enable ultra-thin displays.

The boost controller, with programmable switching frequency from 200kHz to 2.2MHz, maximizes efficiency by dynamically minimizing the output voltage while maintaining LED string current accuracy. It provides excellent line and load response with no external compensation components. An external resistor adjusts the current from 40-240mA per string.

Typical Application Circuit



Pin Configuration



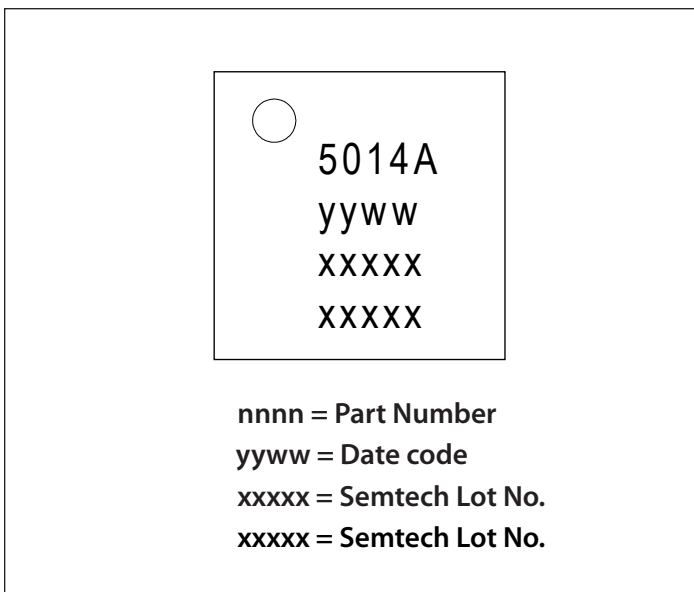
Ordering Information

Device	Package
SC5014AMLTRT ⁽¹⁾⁽²⁾	MLPQ-20 4x4
SC5014AEVB	Evaluation Board

Notes:

- (1) Available in tape and reel only. A reel contains 3,000 devices.
- (2) Lead-free packaging only. Device is WEEE and RoHS compliant, and halogen free.

Marking Information



Absolute Maximum Ratings (refer to PGND)

VCC Pin (V)	-0.3 to +6.0
IO Pins (V)	-0.3 to +30
DRVN, OVP, CS, EN, UVLO, SCP, REF, \overline{FLT} (V) ..	-0.3 to +6.0
FSET, SCL, SDA, ISET, PWMI (V)	-0.3 to +6.0
PGND to AGND (V)	-0.3 to +0.3
ESD Protection Level ⁽¹⁾ (kV)	2

Recommended Operating Conditions

Ambient Temperature Range (°C).....	$-40 \leq T_A \leq +85$
VIN (V)	4.5 to 27
IO Current per String (mA)	250 (max)

Thermal Information

Thermal Resistance, Junction to Ambient ⁽²⁾ (°C/W)	32
Maximum Junction Temperature (°C)	+150
Storage Temperature Range (°C)	-65 to +150
Peak IR Reflow Temperature (10s to 30s) (°C)	+260

Exceeding the above specifications may result in permanent damage to the device or device malfunction. Operation outside of the parameters specified in the Electrical Characteristics section is not recommended.

NOTES:

- (1) Tested according to JEDEC standard JESD22-A114-B.
- (2) Calculated from package in still air, mounted to 3 x 4.5in, 4-layer FR4 PCB with thermal vias under the exposed pad per JESD51 standards.

Electrical Characteristics

Unless noted otherwise, $T_A = 25^\circ\text{C}$ for typical, $-40^\circ\text{C} < T_A = T_J < 85^\circ\text{C}$ for min and max. $V_{CC} = 5\text{V}$, $R_{ISET} = 25.5\text{K}\Omega$, $R_{FSET} = 100\text{K}\Omega$.

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Input Supply						
V _{CC} Supply Voltage	V _{CC}		4.5		5.5	V
V _{CC} Under-Voltage Lockout Threshold	V _{CC-UVLO(TH)}	V _{CC} Voltage Rising		4.2	4.4	V
V _{CC} Under-Voltage Lockout Hysteresis	V _{CC-UVLO(HYS)}	V _{CC} Voltage Falling		180		mV
V _{CC} Quiescent Supply Current	I _{CC(Q)}	EN = 5V, Switching, No Load		2		mA
V _{CC} Supply Current in Shutdown	I _{CC(SD)}	EN = 0V			1	μA
V _{UVLO} Under-Voltage Lockout Threshold	V _{UVLO(TH)}	UVLO Pin Voltage Rising	1.18	1.23	1.28	V
I _{UVLO} Under-Voltage Lockout Hysteresis	I _{UVLO(HYS)}	UVLO Pin Voltage Falling	7	10	13	μA
V _{REF} Bandgap Voltage	V _{REF}		1.20	1.23	1.26	V
External FET Gate Drive						
DRVN High Level	V _{DRVN(H)}	100mA from DRVN to GND	V _{CC} -0.5	V _{CC} -0.2		V
DRVN Low Level	V _{DRVN(L)}	-100mA from DRVN to V _{CC}		0.2	0.5	V
DRVN On-Resistance	R _{DRVN}	DRVN High or Low		2	5	Ω
DRVN Sink / Source Current	I _{DRVN}	DRVN Forced to 2.5V		1		A
Boost Converter						
CS Current Limit Threshold	V _{CS(LIM)}		0.36	0.40	0.44	V
Soft-Start Time ⁽¹⁾	t _{SS}	From EN to End of Soft-Start		4.4		ms

Electrical Characteristics (continued)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Boost Oscillator Frequency	F_{SW}	$R_{FSET} = 100k\Omega$	0.85	1	1.15	MHz
Boost Oscillator Frequency	F_{OSC}	R_{FSET} Varies	0.2		2.2	MHz
Maximum Duty Cycle	D_{MAX}		88	92		%
Control Signals: EN, PWM1, SDA, SCL						
High Voltage Threshold	V_{IH}	$V_{CC} = 4.5V$ to $5.5V$	2.1			V
Low Voltage Threshold	V_{IL}	$V_{CC} = 4.5V$ to $5.5V$			0.8	V
SDA Output Low	$V_{SDA(L)}$	-6mA from V_{CC} to SDA			0.3	V
Pin Leakage Current	I_{LEAK}	$V_{EN} = 0V, V_{PWM1} = V_{ISET} = V_{FSET} = V_{SDA} = V_{SCL} = 5.0V$	-1		1	μA
PWM Dimming Input						
PWMI Input Dimming Frequency	F_{PWM1}		100		30k	Hz
Over-Voltage Protection						
OVP Trip Threshold Voltage	$V_{OVP(TRIG)}$	OVP Rising	1.1	1.2	1.3	V
OVP Hysteresis	$V_{OVP(HYS)}$	OVP Falling		10		mV
OVP Leakage Current	$I_{OVP(LEAK)}$	OVP = 5V		0.1	1	μA
Current Sink (IO)						
IOx Dimming Minimum Pulse Width	$T_{PWM(MIN)}$	$F_{PWM(LED)} = 100Hz - 30kHz$		300		ns
ISET pin Voltage	V_{ISET}			1.23		V
Regulation Voltage	$V_{IOn(REG)}$	Voltage of Regulating String		0.9		V
Current Sink Disable Threshold	$V_{IOn(DIS)}$	Checked at Power-up	0.6			V
Current Sink Rise/Fall Time ⁽¹⁾	$t_{RISE/FALL}$	Rising Edge from 10% to 90% of I_{On}		25		ns
LED Current Accuracy	$I_{On(ACC\%)}$	PWMI = 100%, $T_A = +25^\circ C$	196	200	204	mA
LED Current Matching ⁽²⁾	$I_{On(MATCH)}$	PWMI = 100%, $T_A = +25^\circ C$			± 1.0	%
		PWMI = 100%, $T_A = -40^\circ C, +85^\circ C$			± 2.0	%
I_{On} Off Leakage Current	$I_{On(LEAK)}$	PWMI = 0V, EN = 0V, $V_{IO1} = 25V$		0.1	1	μA

Electrical Characteristics (continued)

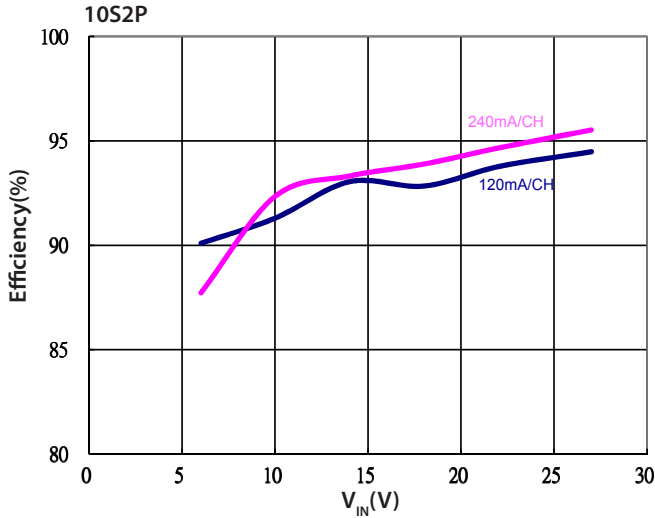
Parameter	Symbol	Conditions	Min	Typ	Max	Units
Fault Protection						
LED Short-Circuit Protection Threshold	$V_{IO(SCP)}$	R_4 and R_5 ⁽³⁾	$17 \times V_{SCP}$	$20 \times V_{SCP}$	$23 \times V_{SCP}$	V
LED Open-Circuit Protection Threshold	V_{IO_OCP}			0.2		V
LED Short-Circuit Fault Delay	$t_{SCP(DELAY)}$	V_{OVP} Set to 1.5V, \overline{FLT} Goes Low		1		μs
\overline{FLT} Pin Leakage Current	$I_{\overline{FLT}(LEAK)}$	$V_{EN} = 0V$, $V_{\overline{FLT}} = 5.0V$	-1		1	μA
\overline{FLT} Output Low	$V_{\overline{FLT}(LOW)}$	-5mA from \overline{FLT} to V_{CC}			0.3	V
Over-Temperature Protection						
Thermal Shutdown Temperature	T_{OTP}			150		$^{\circ}C$
Thermal Shutdown Hysteresis	T_{OTP-H}			10		$^{\circ}C$
I²C Control Interface: SDA, SCL Timing Specifications						
SCL Clock Frequency	F_{SCL}				400	kHz
SCL Clock Low Period	$t_{LOW(SCL)}$		1.3			μs
SCL Clock High Period	$t_{HIGH(SCL)}$		0.6			μs
Hold Time Start Condition	$t_{HD(START)}$		0.6			μs
SDA Setup Time	$t_{SU(SDA)}$		100			ns
SDA Hold Time	$t_{HD(SDA)}$		0		0.9	μs
Setup Time Stop Condition	$t_{SU(STOP)}$		0.6			μs
Bus Free Time Between Stop & Start	t_{BF}		1.3			μs

Notes:

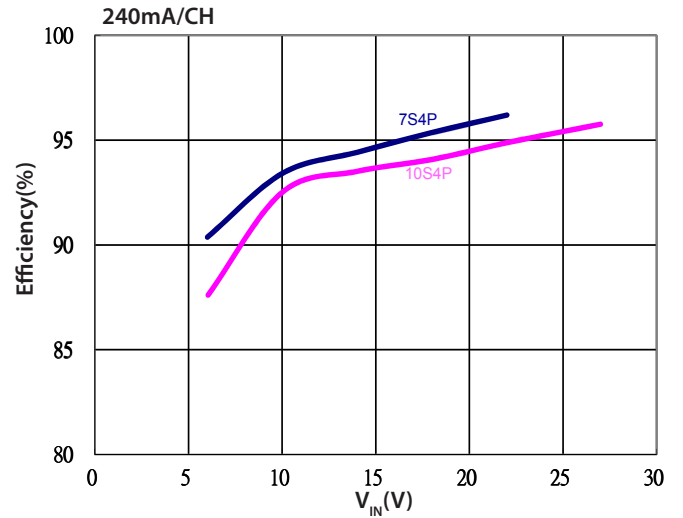
- (1) Ensured by design and characterization, not production tested.
- (2) LED current matching for 2 channels is defined as the largest of the two numbers, i.e., (MAX-AVG)/AVG and (AVG-MIN)/AVG; where MAX is the maximum LED channel current, MIN is the minimum LED channel current and AVG is the average of the 2 LED channel currents.
- (3) Refer to the application circuit on page 20, Figure 2.

Typical Characteristics

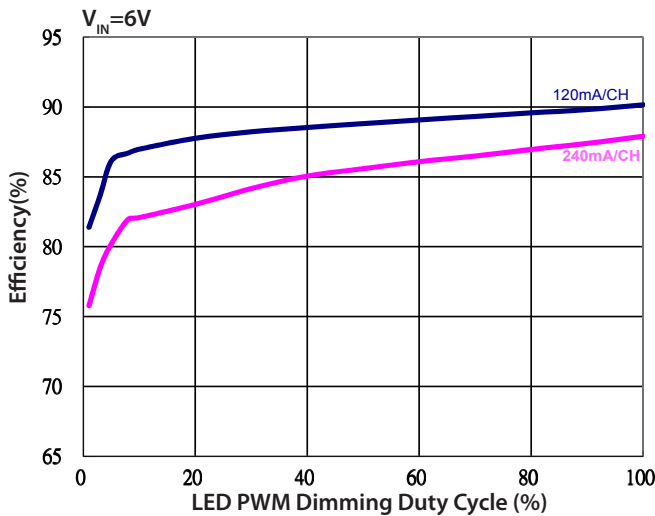
Backlight Efficiency vs. Input Voltage



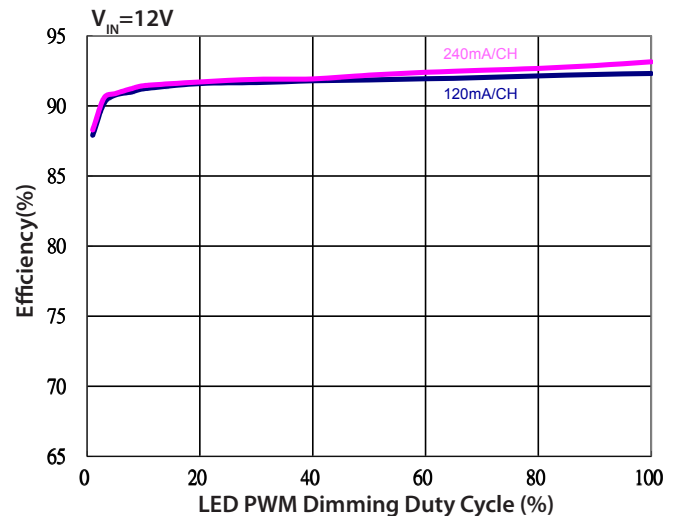
Backlight Efficiency vs. Input Voltage



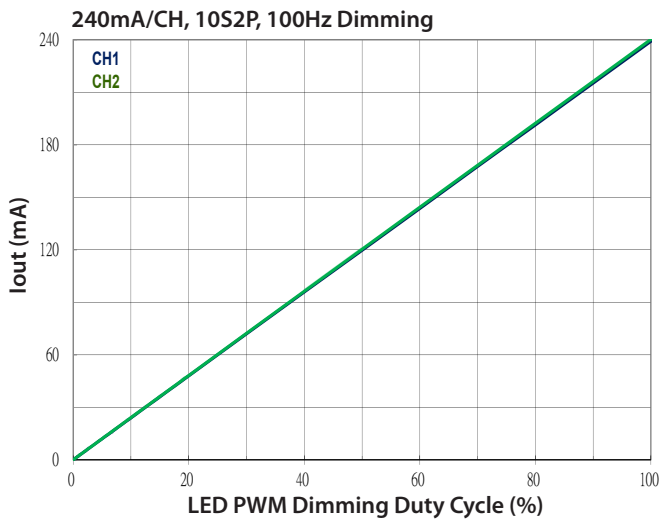
Backlight Efficiency vs. LED String Current



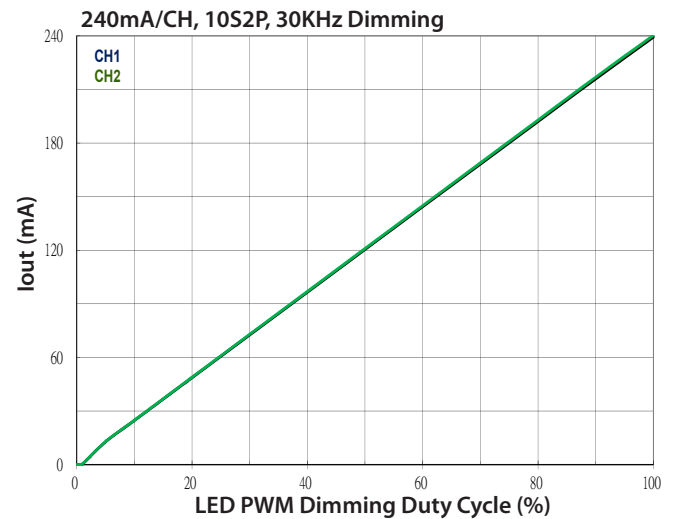
Backlight Efficiency vs. LED String Current



PWM Dimming Linearity

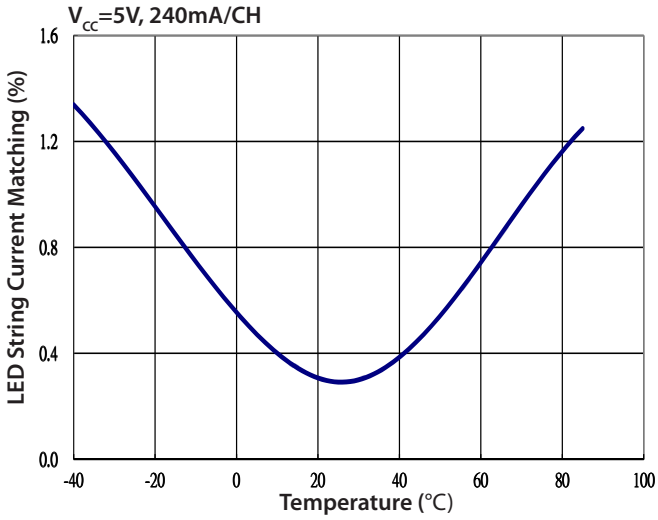


PWM Dimming Linearity

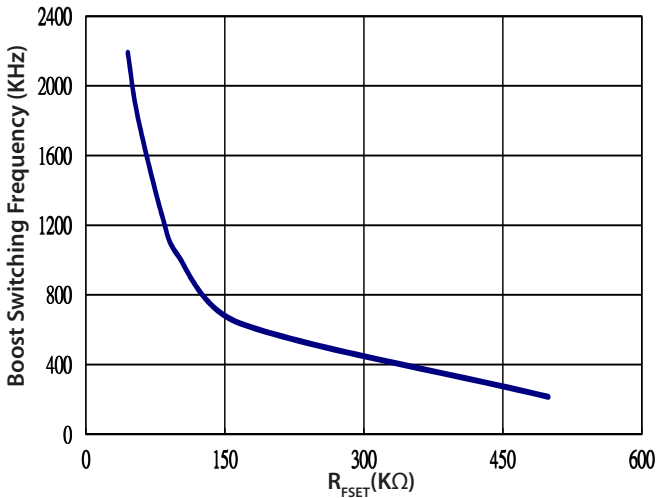


Typical Characteristics (continued)

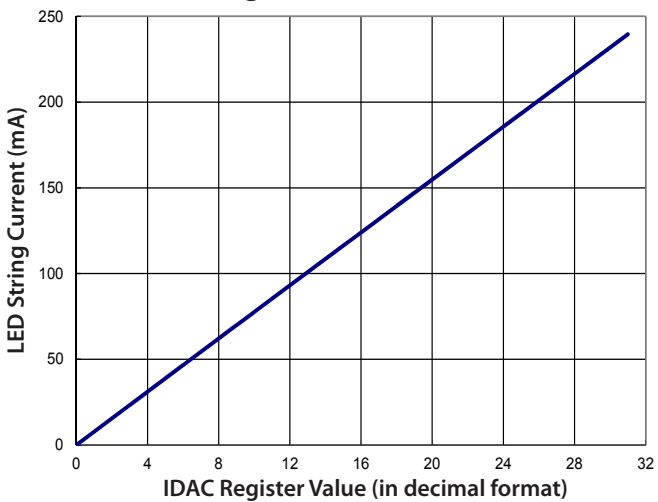
LED String Current Matching vs. Temperature



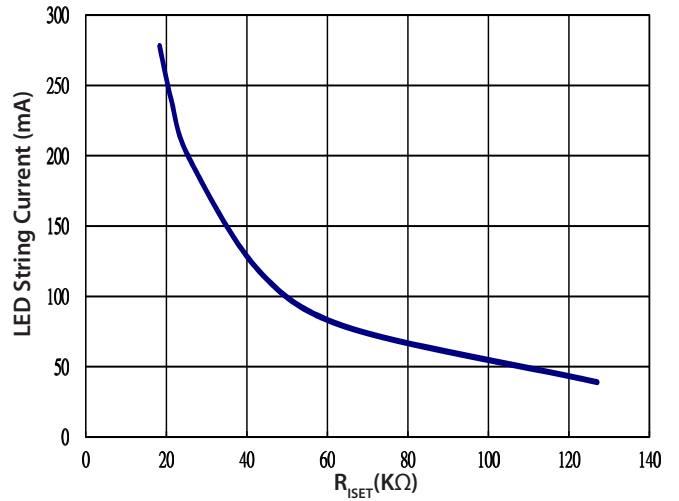
Switching Frequency vs. R_{FSET}



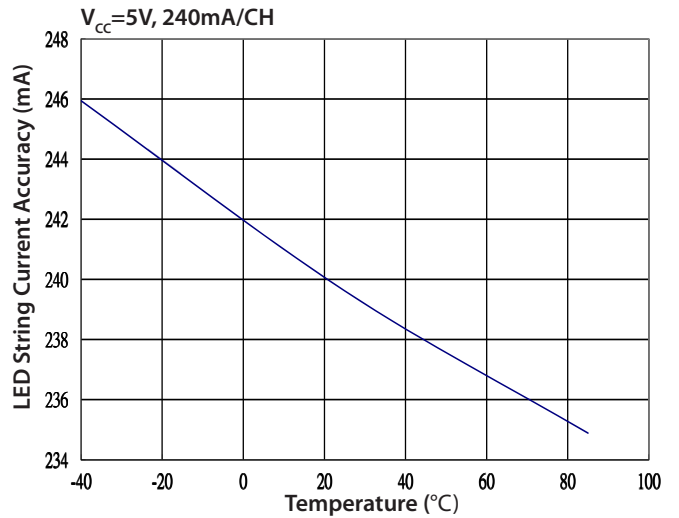
LED String Current vs. Analog Dimming Control Register (IDAC) Value



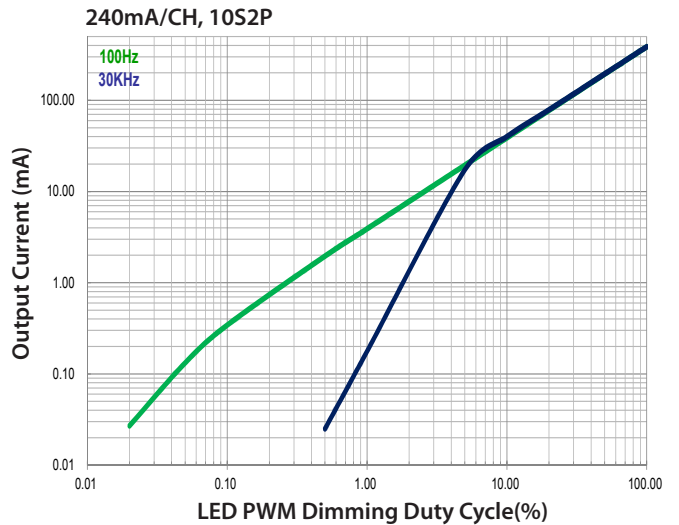
LED String Current vs. R_{ISET}



LED String Current Accuracy vs. Temperature



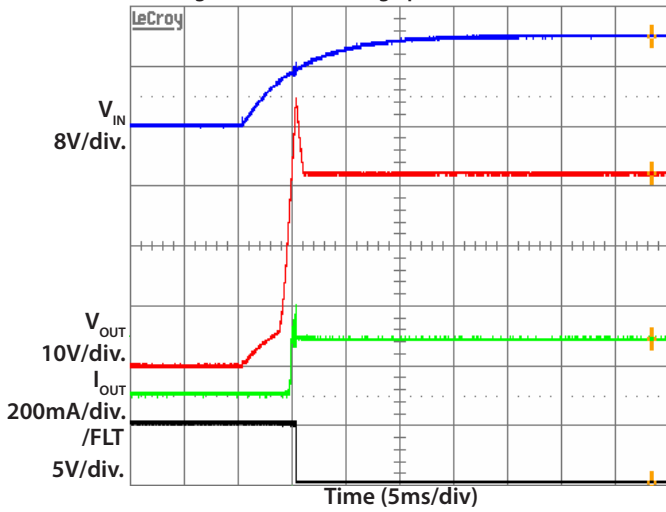
PWM Dimming Linearity



Typical Characteristics (continued)

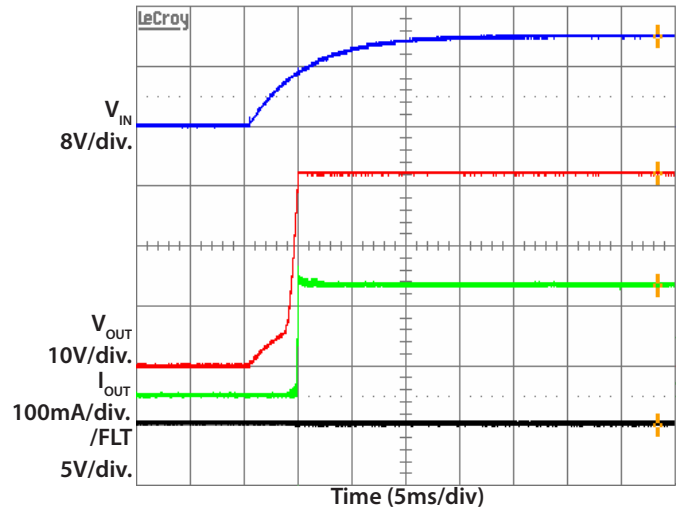
LED Open Circuit Protection

Starting with one LED string open-circuit



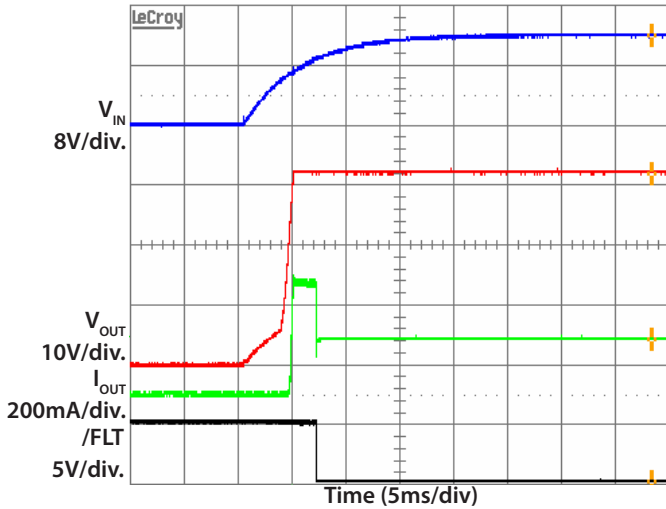
Unused String

Starting with one unused LED string



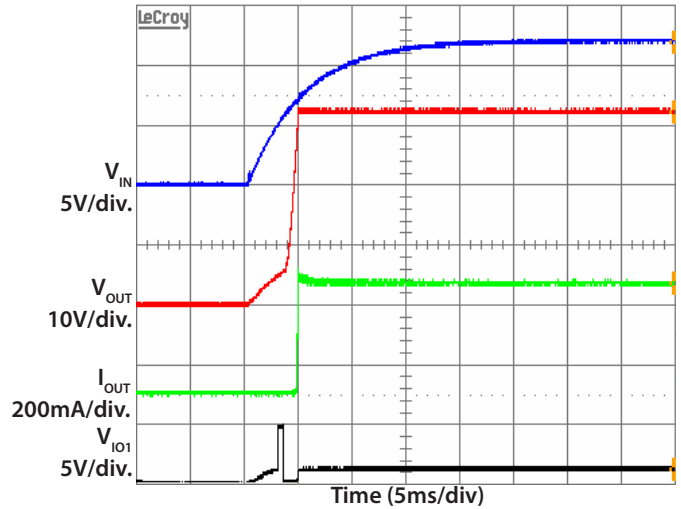
LED Short Circuit Protection

Two LEDs short circuit in one string



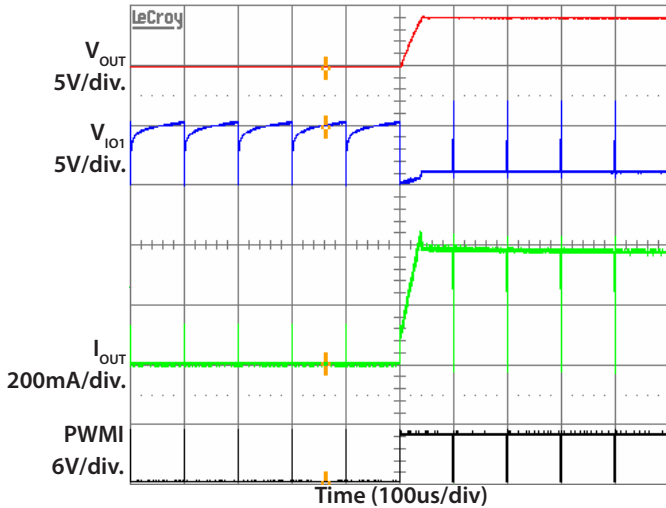
Start Up by Vin

10S2P, 240mA/CH



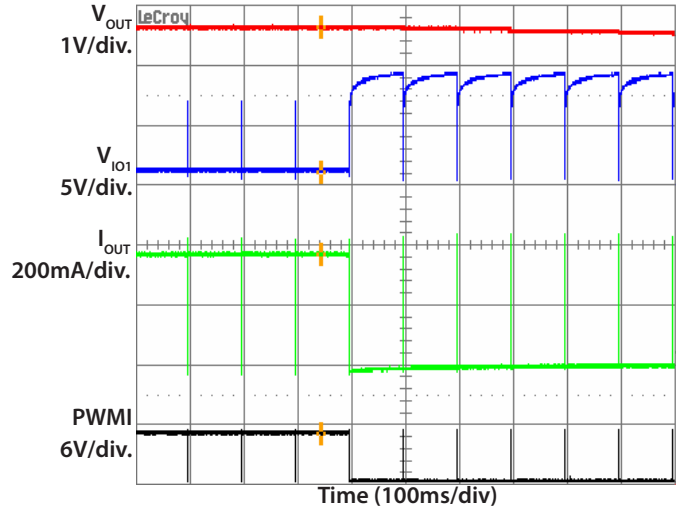
Load Transient Response

PWM(10KHz)=0.5% to 99%, VIN=12V, 200mA/CH X 2



Load Transient Response

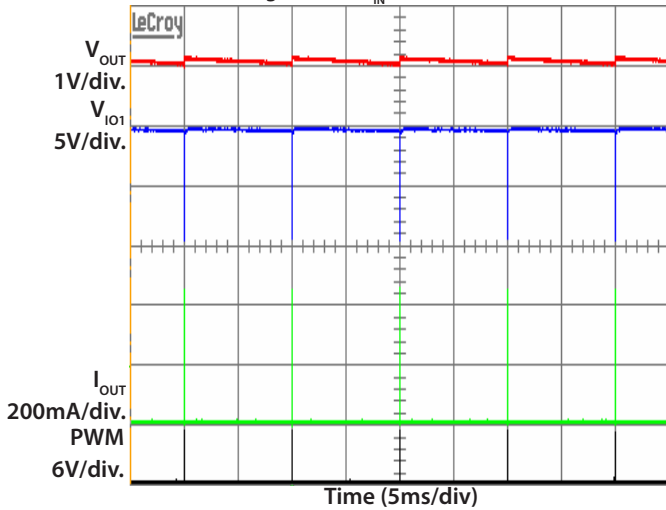
PWM(10KHz)=99% to 0.3%, VIN=12V, 200mA/CH X 2



Typical Characteristics (continued)

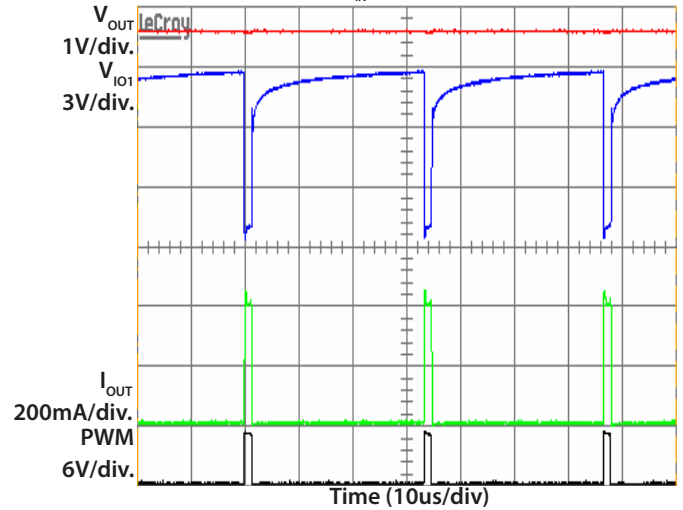
PWM Dimming

0.04% dimming@100Hz, $V_{IN}=12V$, 10S2P, 200mA/CH



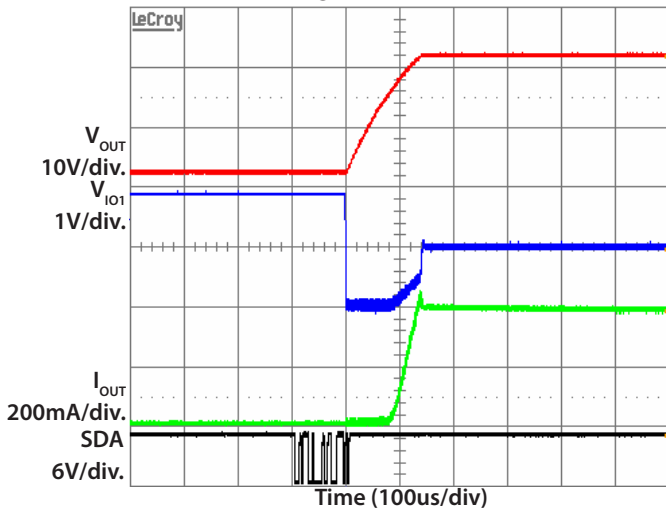
PWM Dimming

4% dimming@30KHz, $V_{IN}=12V$, 10S2P, 200mA/CH



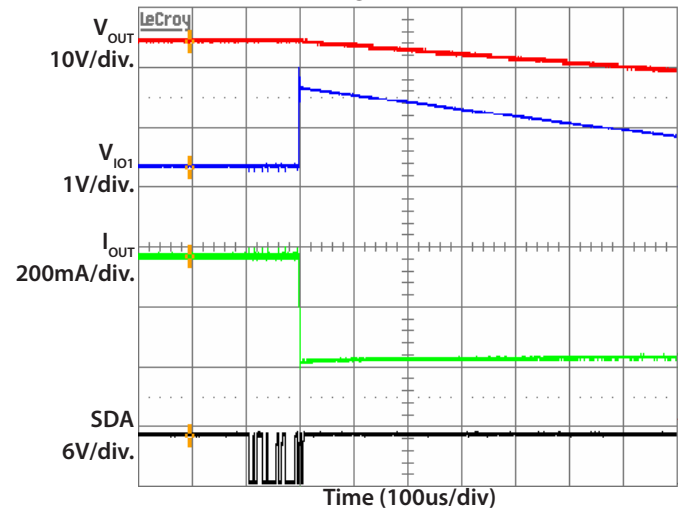
Analog Dimming Transient via I²C

0% to 100% dimming, 200mA/CH



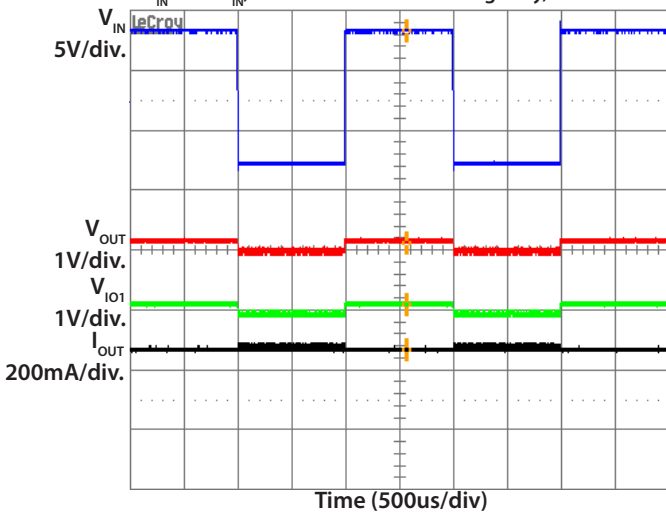
Analog Dimming Transient via I²C

100% to 9.68% dimming, 200mA/CH



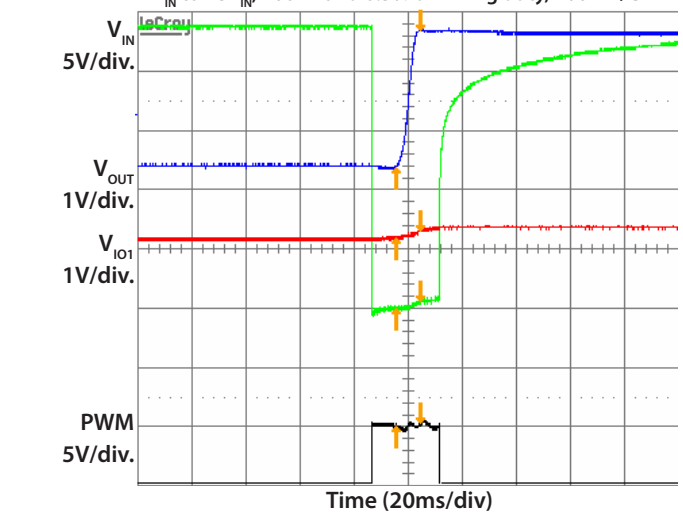
Line Transient Response

7V_{IN} to 18V_{IN}, 200Hz and 100% dimming duty, 200mA/CH



Line Transient Response

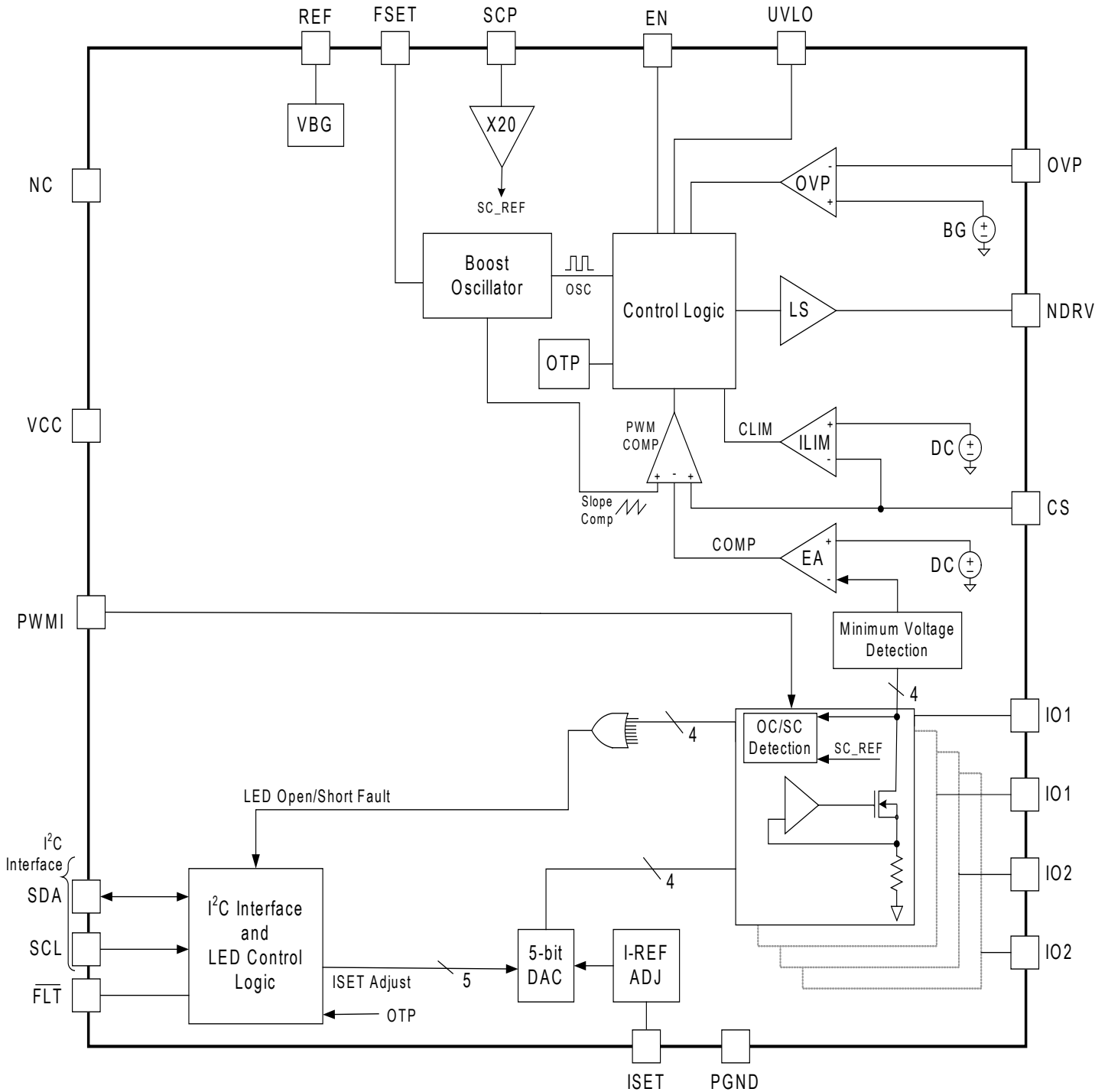
7V_{IN} to 18V_{IN}, 200Hz and 0.5% dimming duty, 200mA/CH



Pin Descriptions

Pin #	Pin Name	Pin Function
1	UVLO	Input under-voltage lockout pin — Device is disabled when this pin is less than 1.23V (nominal). Add a resistor divider from this pin to the input voltage and AGND, respectively.
2	SCP	Short-circuit LED protection programming pin — Shorted LED protection disables the individual channel when the current sink voltage exceeds the programmed voltage threshold. Adding a resistor divider from this pin to REF and PGND programs the shorted-LED protection up to 20x the V_{SCP} voltage. Pulling the pin high to VCC disables the SCP feature on all channels.
3	REF	1.23V reference voltage output pin — Connect a 1 μ F ceramic bypass capacitor from this pin to ground.
4	FSET	Step-up (boost) frequency set pin — Connect a resistor from this pin to ground to set the frequency from 200kHz to 2.2MHz.
5	NC	No connect. This can be left floating or connected to GND.
6	SCL	I ² C serial clock input — This pin must be connected to ground if not used.
7	SDA	I ² C serial data input — This pin must be connected to ground if not used.
8	ISET	LED current programming pin — Connect an external resistor to ground to program the current in the LED strings. For more details please refer to LED String Peak Current Programming on page 13.
9	$\overline{\text{FLT}}$	Logic low fault status pin — Open-drain output is latched low when fault condition is detected: Open/Short LED, Shorted String, OVP or OTP. Fault status can be reset by removing fault condition(s) and toggling the EN, VCC or UVLO pins. This pin can be left floating if not used.
10	PWMI	LED string PWM dimming control input.
11 ~14	IO2 ~ IO1	Regulated current sink LED channel 2 to channel 1 respectively . Connect the related IO pin to the cathode of the bottom LED in string 2 to string 1 respectively. Connect the related IO pin to ground to disable the related LED string during power on.
15	OVP	Over-voltage feedback pin — Over-voltage activated when pin voltage exceeds 1.2V. Use a resistor divider tied to the output and GND to set the OVP level.
16	CS	Step-up (boost) switch current sense pin — Connect a resistor from this pin to ground for current sense - utilized in peak current mode control loop and over-current sense circuitry.
17	PGND	Power ground — Tie this pin to the power ground plane close to input and output decoupling capacitors.
18	NDRV	Gate drive for the external step-up (boost) N-Channel MOSFET.
19	VCC	Input bias voltage supply for the IC — Accepts 4.5-5.5V inputs. Add a 1 μ F or larger ceramic bypass capacitor from this pin to ground.
20	EN	Logic high enable pin — Pull logic high to enable the device or pull low to disable and maintain low shutdown current.
-	PAD	AGND thermal pad for heatsinking purposes — It should be connected to ground plane for proper circuit operation.

Block Diagram



Applications Information

General Description

The SC5014A contains a high frequency, current-mode, internally compensated boost controller with 2 constant current sinks for driving LED strings. The LED current for both strings is programmed by an external resistor. The boost converter operates to maintain minimal required output voltage for regulating the LED current to the programmed value. A typical backlight application uses 3 to 14 LEDs per each string, with current driven up to 240mA. The unique control loop of the SC5014A allows fast transient response in dealing with line and load disturbances. The SC5014A, operating with an external power MOSFET, regulates the boost converter output voltage based on the instantaneous requirement of the 2 string current sources. This provides power to the entire lighting subsystem with increased efficiency and reduced component count. It supports PWM dimming frequencies from 100Hz to 30kHz and the supply current is reduced to 2mA typical when both LED strings are off.

Start-Up

When the EN pin is pulled up high (>2.1V), the device is enabled and the UVLO and VCC pin voltages are checked. The VCC voltage has fixed under-voltage rising and falling trip points. If the VCC pin is higher than 4.2V and the UVLO pin voltage is greater than 1.23V, the SC5014A goes into a start-up sequence. The UVLO pin voltage can be used to program the input power source voltage VIN turn-on threshold and its hysteresis (refer to the detailed application circuit on page 20, Figure 2) as shown by the following equations:

$$V_{IN_TurnOn} [V] = 1.23 \times (R_1 + R_2) / R_1$$

$$V_{IN_Hysteresis} [V] = 10^{-5} \times R_2 [\Omega]$$

In the next phase, the SC5014A checks each IO pin to determine if the respective LED string is enabled. Each IO pin is pulled up with a 100µA current source. If any IO pin is connected to ground, it will be detected as an unused string, and will be turned off. This unused string checking procedure typically takes 1ms. After this, the SC5014A enters into a soft-start sequence.

The soft-start function helps to prevent excess inrush current through the input rail during start-up. In the SC5014A, the soft-start is implemented by slowly ramping up the reference voltage fed to the error amplifier. This closed loop start-up method allows the output voltage to ramp up without any overshoot. The duration of the soft-start in the SC5014A is controlled by an internal timing circuit, which is used during start-up and is based on the boost converter switching frequency. For example, with switching frequency at 1MHz, it is 8ms typical and becomes 4ms typical when the switching frequency is 2MHz.

If the PWM voltage goes low while the SC5014A is in soft-start operation, the SC5014A switches to standby mode, where the external power MOSFET and the LED current sources will be turned off immediately. The internal soft-start timer is turned off and the soft-start value is saved. When the PWM voltage goes high again, the soft-start resumes from the previously saved value.

Each LED current source tries to regulate the LED current to its set point. The control loop will regulate the output voltage such that all the IO pin voltages are at least 0.9V typical.

Shutdown

When the EN pin is pulled down below 0.8V, the device enters into shutdown mode. In this mode, all the internal circuitry is turned off and the supply current is less than 1µA (max).

In the scenario where the EN pin voltage is high, but VCC voltage falls below the respective UVLO threshold, the SC5014A goes into a suspend mode. In this mode, all the internal circuitry except the reference and the oscillator are turned off.

Thermal Shutdown (TSD)

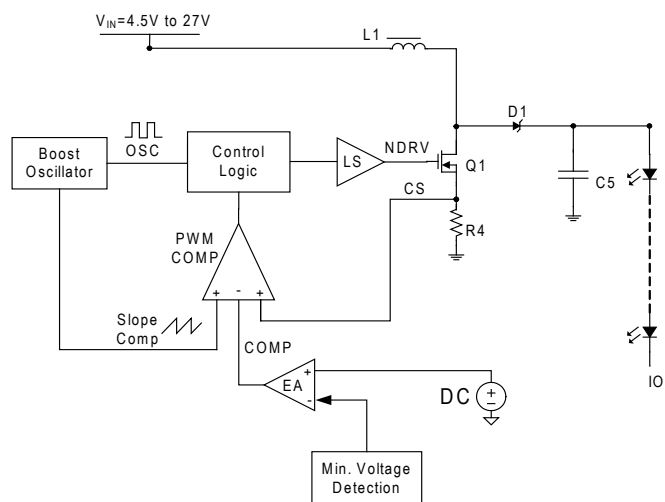
If the thermal shutdown temperature of typical 150°C is reached, the boost converter and all IO current sources are turned off. The \overline{FLT} pin is forced low in this condition. When the temperature falls below the TSD trip point by 10°C, the SC5014A will restart following the start-up sequence as described before. The \overline{FLT} pin is latched and will stay low, it is reset by cycling the EN, VCC or UVLO.

Applications Information (continued)

Boost Converter Operation

The SC5014A includes a boost controller with programmable switching frequency. It applies a current-mode control method with an integrated compensation loop as shown in the diagram below. The clock (see block diagram on page 11) from the oscillator sets the latch and turns on the external power MOSFET, which serves as the main power switch. The current flowing through this switch is sensed by the current sense resistor in series with the switch. The sensed switch current is summed with the slope-compensated ramp and fed into the modulating input of the PWM comparator. When the modulating ramp intersects the error amplifier output (COMP), the latch is reset and the power MOSFET is turned off. The sense resistor also sets the peak current limit of the power MOSFET, I_{OCP} using the following equation:

$$I_{OCP} [A] = 0.4 / R_{CS} [\Omega]$$



The current-mode control system contains two loops. For the inner current loop, the error amplifier (EA) output (COMP) controls the peak inductor current. In the outer loop, the EA regulates the output voltage for driving the LED strings.

Boost Converter Switching Frequency Selection

The resistor between FSET and GND sets the boost converter switching frequency (200kHz to 2.2MHz) using the following equation:

$$f_{SW} [kHz] = 10^5 / R_{FSET} [k\Omega]$$

A higher switching frequency allows the use of low-profile height inductors for space-constrained and cost-sensitive applications.

Over-Voltage Protection (OVP)

The SC5014A features programmable output over-voltage protection to prevent damage to the IC and output capacitor in the event of a LED string open-circuit. The boost converter output voltage is sensed at the OVP pin through the resistor voltage divider. The OVP trip threshold (refer to detailed application circuit on page 20, Figure 2) can be calculated using the following equation:

$$\text{OVP Trip Voltage [V]} = 1.2 \times (R_{11} + R_{12}) / R_{12}$$

When the OVP pin voltage exceeds 1.2V, the boost converter turns off and the $\overline{\text{FLT}}$ pin is pulled low. When the OVP pin voltage falls below the OVP threshold (falling), the boost converter restarts and the $\overline{\text{FLT}}$ pin is released. There is 10mV hysteresis between the OVP pin threshold (falling) and the OVP pin threshold (rising). This results in an output voltage hysteresis expressed as:

$$\text{Output OVP Hysteresis [mV]} = 10 \times (R_{11} + R_{12}) / R_{12}$$

LED Current Sink

The SC5014A provides 2 current sinks and each can sink up to 240mA current. It incorporates LED string short-circuit protection (trip-level programmable; can be disabled) and LED string open-circuit protection.

LED String Peak Current Programming

LED string peak current (at 100% dimming) can be set by selecting resistor R_{ISET} connected between ISET and GND. The relationship between R_{ISET} resistance and single LED string peak current is calculated using the following equation:

$$I_{LED} [mA] = 2 \times (1036 \times 1.23) / R_{ISET} [k\Omega]$$

The string current can be programmed up to 240mA.

LED Connection

Two strings of LEDs can be connected to pin IO1 and pin IO2. Pins IO1,2 should stay connected.

Unused Strings

The SC5014A may be operated with less than 2 strings. In this mode of operation, the unused IO pin should be connected to ground. During start-up, these unused strings are detected and disabled while other active strings work normally, and $\overline{\text{FLT}}$ does not get pulled low.

Applications Information (continued)

LED Short-Circuit Protection (SCP)

The SC5014A features a programmable LED short-circuit protection (SCP). This allows the part to be customized based on the LED forward voltage (V_f) mismatches between the LED strings. If one or more LEDs are detected as short-circuited, the corresponding string will be latched off. The voltages on both IO pins are monitored to check if any IO pin exceeds the SCP trip point. The IO voltage for LED string(s) with faulty short-circuit LED(s) will be higher than other normal IO pin voltage. This LED short-circuit protection trip level (see detailed application circuit on page 20, Figure 2) is expressed by the following equation:

$$V_{SCP_Trip} [V] = 20 \times (1.23 \times R_4) / (R_4 + R_5)$$

If any IO pin voltage exceeds the trip voltage, the IO current sink will be latched off and the \overline{FLT} will go low. This latch can be reset by cycling UVLO, VCC or EN. Other LED string is unaffected and continue in normal operation. This protection will be disabled if SCP is tied to VCC.

There is a typical 10 μ s SCP detection time in PWM dimming applications. If the PWM dimming on-time is less than the SCP detection time, the SCP cannot be enabled.

In many applications, LED strings are connected to the IO pins through a mechanical connector, which cannot support an electrical connection at specific times. This connection might cause noise on the IO pins. If this noise is large enough, it may trigger a false SCP mode. Under such condition, a ceramic decoupling capacitor (100pF ~ 8.2nF) between IO pin to ground can help prevent the SC5014A from entering the protection mode by false trigger. Or, simply disable this feature by connecting SCP pin to VCC pin.

LED Open-Circuit Protection

If any LED string becomes open, the respective IO pin voltage will be pulled to ground. Consequently, the internal COMP node (output of error amplifier) is driven high, which causes the boost output voltage to increase. The output voltage will be eventually clamped to a voltage set by the OVP resistor divider. Under this condition, the faulty string is latched off and the \overline{FLT} pin is pulled low. The boost voltage gets regulated to the voltage required to set all non-faulty IO pins above 0.9V (typ). The other string remain in normal operation. The \overline{FLT} and the faulty LED

current sink latch-off can be reset by cycling UVLO, VCC or EN.

LED Analog Dimming Control

The LED current in SC5014A can be dimmed via the 5-bit analog dimming register (register address: 0x02). The LED current can be adjusted in 32 steps from 0mA to maximum value, which is determined by the R_{SET} resistor.

The SC5014A has a unique DAC architecture which allows it to have excellent LED current accuracy and string-to-string matching over the entire DAC range.

The analog dimming method can be used in conjunction with PWM dimming to increase the dimming resolution. The fast loop response of the SC5014A allows the LED current to transition to a new value within 160 μ s or so. Please refer to the graphs in the typical characteristics section.

LED PWM Dimming Control

The PWM input needs to be held high for normal operation. PWM dimming can be achieved by cycling the PWM input at a given frequency where a "low" on the PWM input turns off both IO current sinks and a "high" turns on all IO current sinks. The PWM pin can be toggled by external circuitry to allow PWM dimming. In a typical application, a microcontroller sets a register or counter that varies the pulse width on a GPIO pin. The SC5014A allows dimming over a wide frequency range (100Hz-30kHz) in order to allow compatibility with a wide range of devices. This includes the newest dimming strategies that avoid the audio band by using high frequency PWM dimming. In this manner, a wide range of illumination can be generated while keeping the instantaneous LED current at its peak value for high efficiency and color temperature. The SC5014A provides a 1000:1 dimming range at 1kHz PWM frequency. The LED current sinks turn on/off very rapidly (<25ns, typical). This allows a wide dimming ratio. An additional advantage of PWM dimming is that it avoids in-rush currents when filling the boost output capacitor. Simply apply the PWM signal to the device at 10% duty for a millisecond or two, and in-rush current is reduced. This dimming time will vary based on the number of LEDs and the size of the output capacitor. This can be easily determined during testing and programmed into the microcontroller firmware.

Table 1 — Fault Protection Descriptions

Type of Fault	User Disable?	Fault Criteria	Action on Fault		Recovery	
			Device	FLT pin (latching / non-latching)	Condition(s)	FLT pin
Input Under-voltage at VIN (UVLO)	No	$V_{IN} < (1 + R_2/R_1) \times 1.23$ (rising)	No Startup	Not Active	$V_{UVLO} > 1.23V$ (rising)	High
	No	$V_{IN} < (1 + R_2/R_1) \times 1.23V - I_{UVLO} \times R_1$ (falling)	Shutdown	Not Active	$V_{UVLO} > 1.23V$ (rising)	High
Input Under-voltage at VCC (UVLO)	No	$VCC < 4.2V$ (rising)	No Startup	Not Active	$VCC > 4.2V$ (rising)	High
	No	$VCC < 4.0V$ (falling)	Shutdown	Not Active	$VCC > 4.2V$ (rising)	High
Over-voltage Protection (OVP)	No	$V_{OVP} > 1.23V$ (rising)	Regulate to OVP threshold: $I_{O(n)} = \text{"on"}$	Low (non-latching)	$V_{OVP} < 1.22V$ (falling)	High on removal of fault condition
Over-current Protection (OCP)	No	$V_{CS} > 0.4V$	Limit Q1 FET drain current $< 0.4V/R9$ (typ) ⁽¹⁾	High	$V_{CS} > 0.4V$	High
Shorted LED(s)	Yes, tie SCP to VCC	$V_{IO(n)} > 20 \times V_{SCP}$	Device on: $I_{O(n)} = \text{"off"}$ Other $I_{O(All)} = \text{"on"}$	Low (latching)	Replace Shorted LED(s) and Toggle EN, VCC or UVLO	High
		$V_{IO(All)} > 20 \times V_{SCP}$	Device latch-off; $I_{O(All)} = \text{"off"}$	Low (latching)	Replace Shorted LED(s) and Toggle EN, VCC or UVLO	High
Open LED(s)	No	$V_{IO(n)} < 0.1V$ and OVP event	Device on: $I_{O(n)} = \text{"off"}$ Other $I_{O(All)} = \text{"on"}$	Low (latching)	Replace Open LED(s) and Toggle EN, VCC or UVLO	High
		$V_{IO(All)} < 0.1V$ and OVP event	Device latch-off; $I_{O(All)} = \text{"off"}$	Low (latching)	Replace Open LED(s) and Toggle EN, VCC or UVLO	High
Unused Strings	No	$V_{IO(All)} < 0.1V$ (start up)	Device on: $I_{O(n)} = \text{"off"}$ Other $I_{O(All)} = \text{"on"}$	High		
Over-Temperature Protection (OTP)	No	$T_J > 150^\circ C$ (typ)	Device off; $I_{O(All)} = \text{"off"}$	Low (latching)	Satisfy $T_{HYS} > 10^\circ C$; Device On; $I_{O(All)} = \text{"on"}$; Toggle EN, VCC or UVLO	High

Note: Refer to the application circuit example for R_1 and R_2 on page 20, Figure 2.

Applications Information (continued)

Fault Protection

The SC5014A provides fault detection for low supply voltage, LED related faults, boost converter over-voltage and thermal shutdown. The open drain output pin ($\overline{\text{FLT}}$) indicates a system fault. The nature of the fault can be read from the fault status resistor (register address: 0x00) via I²C interface. Refer to Table 1 for a description of the Fault Protection Modes.

Other Possible Configurations

Depending on different application requirements, the SC5014A can also be easily configured to other topologies, such as the SEPIC configuration shown in Figure 4, page 21.

Li-Ion Powered Display Configuration

If a Li-Ion powered display application is required, V_{CC} is needed to power with 5V. However, V_{IN} can be set lower from 3V to 4.2V for example. An advantage of this type of configuration is that it provides higher efficiency. Please use Figure 3 on page 20 for reference.

High Output Voltage Configuration

If a high output voltage application is required, an additional external cascode MOSFET can be added on each IO pin to meet such requirement, please refer to Figure 5 on page 21 for reference.

In this case, the upper limit on the output voltage is mainly determined by the rating of the external MOSFET, heat dissipation, etc.

PCB Layout Considerations

The placements of the power components outside the SC5014A should follow the layout guidelines of a general boost converter. The Detailed Application Circuit is used as an example.

1. Capacitor (C2) should be placed as close as possible to the VCC and AGND to achieve the best performance.
2. Capacitor (C1) is the input power filtering capacitor for the boost. It needs to be tied to PGND.
3. The converter power train inductor (L1) is the boost converter input inductor. Use wide and short traces connecting these components.
4. The output rectifying diode (D1) uses a Schottky diode for fast reverse recovery. Transistor (Q1) is the external switch. Resistor (R9) is the switch current sensing resistor. To minimize switching noise for the boost converter, the output capacitor (C6) should be placed such that the loop formed by Q1, D1, C6 and R9, is minimized. The output of the boost converter is used to power up the LEDs. Use wide and short trace connecting Pin NDRV and the gate of Q1. The GNDs for R9 and C6 should be PGND. These components should be close to the SC5014A.
5. Resistor (R8) is the output current adjusting resistor for IO1 through IO2 and should return to AGND. Place it next to the IC.
6. Resistor (R6) is the switching frequency adjusting resistor and should return to AGND. Place it next to the IC.
7. The decoupling capacitor (C3) for Pin REF should return to AGND. Place it next to the IC.
8. Resistors (R4, R5) form a divider to set the SCP level, R4 should return to AGND. Place it next to the IC.
9. Resistors (R2, R1) form a divider to set the UVLO level for UVLO pin. R1 should return to AGND. Place it next to the IC.
10. R11 and R10 form a divider to set the OVP level for VOUT, R10 should return to AGND. Place it next to the IC.
11. All the traces for components with AGND connection should avoid being routed close to the noisy areas.
12. An exposed pad is located at the bottom of the SC5014A for heat dissipation and analog ground. A copper area underneath the pad is used for better heat dissipation. On the bottom layer of the PCB another copper area, connected through vias to the top layer, is used for better thermal performance. The pad at the bottom of the SC5014A should be connected to AGND. AGND should be connected to PGND at a single point for better noise immunity.

Components Selection

Inductor Selection

The choice of the inductor affects the converter's steady state operation, transient response, and its loop stability. Special attention needs to be paid to three specifications of the inductor, its value, its DC resistance and saturation current. The inductor's inductance value also determines the inductor ripple current. The boost converter will operate in either CCM (Continuous Conduction Mode) or DCM (Discontinuous Conduction Mode) depending on its operating conditions. The inductor DC current or input current can be calculated using the following equation.

$$I_{IN} = \frac{V_{OUT} \times I_{OUT}}{V_{IN} \times \eta}$$

I_{IN} - Input current; I_{OUT} - Output current;

V_{OUT} - Boost output voltage;

V_{IN} - Input voltage;

η - Efficiency of the boost converter

Then the duty ratio under CCM is shown by the following equation.

$$D = \frac{V_{OUT} - V_{IN} + V_D}{V_{OUT} + V_D}$$

V_D - Forward conduction drop of output rectifying diode

When the boost converter runs under DCM ($L < L_{boundary}$), it has the advantages of small inductance and quick transient response; where as if the boost converter works under CCM ($L > L_{boundary}$), normally the converter has higher efficiency.

When selecting an inductor, another factor to consider is the peak-to-peak inductor current ripple, which is given by the following equation:

$$\Delta I_L = \frac{V_{IN} \times D}{f_{SW} \times L}$$

Usually this peak-to-peak inductor current ripple can be chosen between 30% to 50% of the maximum input DC current. This gives the best compromise between the inductor size and converter efficiency. The peak inductor current can be calculated using the following equation:

$$I_{L-peak} = I_{IN} + \frac{V_{IN} \times D}{2 \times f_{SW} \times L}$$

For most applications, an inductor with a value of 2.2 μ H to 22 μ H should be acceptable, (refer to the detailed application circuit on page 20, Figure 2). The inductor peak current must be less than its saturation rating. When the inductor current is close to the saturation level, its inductance can decrease 20% to 35% from the 0A value depending on the vendor specifications. Using a small value inductor forces the converter in DCM, in which case the inductor current ramps down to zero before the end of each switching cycle. It reduces the boost converter's maximum output current and produces a larger input voltage ripple. The DCR of the inductor plays a significant role for the total system efficiency and usually there is a trade-off between the DCR and size of the inductor. Table 2 lists some recommended inductors and their vendors.

Table 2. Recommended Inductors

Inductor	Vendor Website
HCM0703, 2.2uH~10uH	www.cooperindustries.com
IHLP-2525CZ-01, 4.7uH~10uH	www.vishay.com
MLPC0730L, 2.2uH~4.7uH	www.nec-tokin.com/english

Output Capacitor Selection

The next design task is targeting the proper amount of output ripple voltage due to the constant-current LED loads. Usually X5R or X7R ceramic capacitor is recommended. The ceramic capacitor minimum capacitance needed for a given ripple can be estimated using the following equation:

$$C_{OUT} = \frac{(V_{OUT} - V_{IN}) \times I_{OUT}}{V_{OUT} \times f_{SW} \times V_{RIPPLE}}$$

Application Information (continued)

V_{RIPPLE} – Peak to peak output ripple.

The ripple voltage should be less than 200mV (pk-pk) to ensure good LED current sink regulation. For example, a typical application where 240mA/string current is needed, the total output current for 2 channels will be 480mA, and 6x 4.7 μ F capacitors are recommended.

During load transient, the output capacitor supplies or absorbs additional current before the inductor current reaches its steady state value. Larger capacitance helps with the overshoot/undershoot during load transient and loop stability.

Input Capacitor Selection

X5R or X7R ceramic capacitor is recommended for input bypass capacitor. A 1 μ F capacitor is sufficient for the VCC input. Bypass the VIN input with a 10 μ F or larger ceramic capacitor.

Output Freewheeling Diode Selection

Schottky diodes are the ideal choice for the SC5014A due to their low forward voltage drop and fast switching speed. Table 3 shows several different Schottky diodes that work properly with the SC5014A. Verify that the diode has a voltage rating greater than the maximum possible output voltage. The diode conducts current only when the power switch is turned off. The diode must be rated to handle the average output current. A diode rated for 1A average current will be sufficient for most designs.

Table 3. Recommended Rectifier Diodes

Rectifier Diode	Vendor Website
DFLS140	www.diodes.com
SS14/15/16, SS24/25/26	www.vishay.com

External Power MOSFET Selection

The boost converter in SC5014A uses an external power MOSFET to regulate the output voltage and output power to drive LED loads. This boost switching structure has an advantage in that the SC5014A is not exposed to high voltage. Only the external power MOSFET, freewheeling

diode and the inductor will be exposed to the output voltage. The external power MOSFET should be selected with its voltage rating higher than the output voltage by minimum 30%. The current rating should be enough to handle the inductor peak current. Low $R_{\text{DS(on)}}$ MOSFETs are preferred for achieving better efficiency.

The GD (gate driver) on SC5014A provides 1A (peak) current driving capability which is suitable for most MOSFETs for high frequency operation. The average current required to drive the MOSFET is given by the following equation.

$$I_{\text{GATE}} = Q_{\text{G}} \times f_{\text{SW}}$$

Q_{G} — Gate charge

The $R_{\text{DS(ON)}}$ and its RMS current $I_{\text{S,RMS}}$ of the power MOSFET will generate the conduction loss using the following equation.

$$P_{\text{COND}} = I_{\text{S,RMS}}^2 \times R_{\text{DS(on)}}$$

The MOSFET's switch loss can be calculated using the following equation.

$$P_{\text{SW}} = \frac{1}{2} \times V_{\text{IN}} \times I_{\text{L,PEAK}} \times f_{\text{SW}} \times (T_{\text{ON}} + T_{\text{OFF}})$$

Where T_{ON} and T_{OFF} are the MOSFET's on and off time and they can be estimated by the following equations.

$$T_{\text{ON}} = t_r + \frac{Q_{\text{gd}}}{(5 - V_{\text{plateau}}) / (5 + R_g)}$$

$$T_{\text{OFF}} = t_f + \frac{Q_{\text{gd}}}{V_{\text{plateau}} / (5 + R_g)}$$

Where t_r , t_f , Q_{gd} and V_{plateau} can usually be found from data-sheet of the selected MOSFET. R_g is the resistance of the optional resistor connected in series on the gate of the MOSFET.

Components Selection (continued)

Current Sensing Resistor Selection

The switch current is sensed via the current sensing resistor, R_{CS} . The sensed voltage at this pin is used to set the peak switch current limit and also used for steady state regulation of the inductor current. The current limit comparator has a trip voltage of 0.4V (typical). R_{CS} value is chosen to set the peak inductor and switch current using the following equation.

$$I_{SW(Peak)}^2 = 0.4/R_{CS}$$

The power dissipation in R_{CS} can be calculated using the following equations.

$$P_{R_{CS}} = I_{RMS}^2 \times R_{CS}$$

$$I_{RMS} = D \times [I_O / (1-D)]^2$$

I_O = Output DC Current, D = Duty Cycle

For the typical application circuit shown in the detailed application circuit (page 20, Figure 2), the power dissipation on the sensing resistor is shown by the following equations.

Assuming $V_{IN} = 6V$ and $V_{OUT} = 31.5V$, thus $D = 81\%$,

$$P_{R_{CS}} = 0.81 \times (0.48/0.19)^2 \times 0.08 = 0.414(W)$$

For this example, a 0.08Ω 1% thick-film chip resistor rated at 1W can be used.

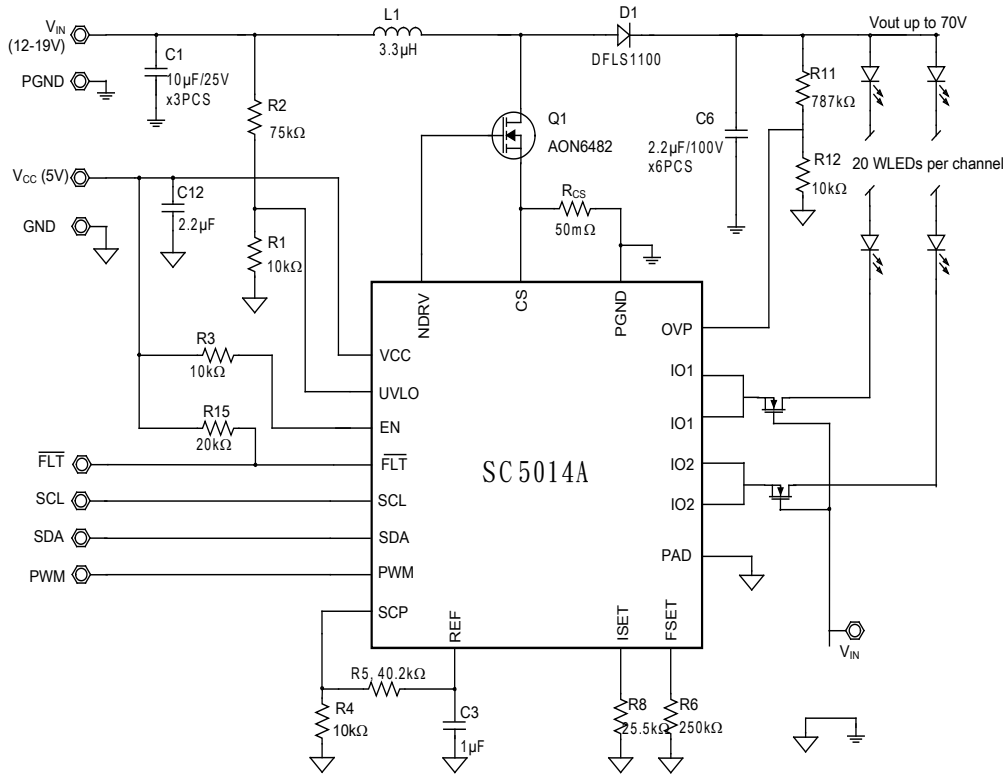


Figure 2— Application Circuit Example, 20 LED @ 200mA

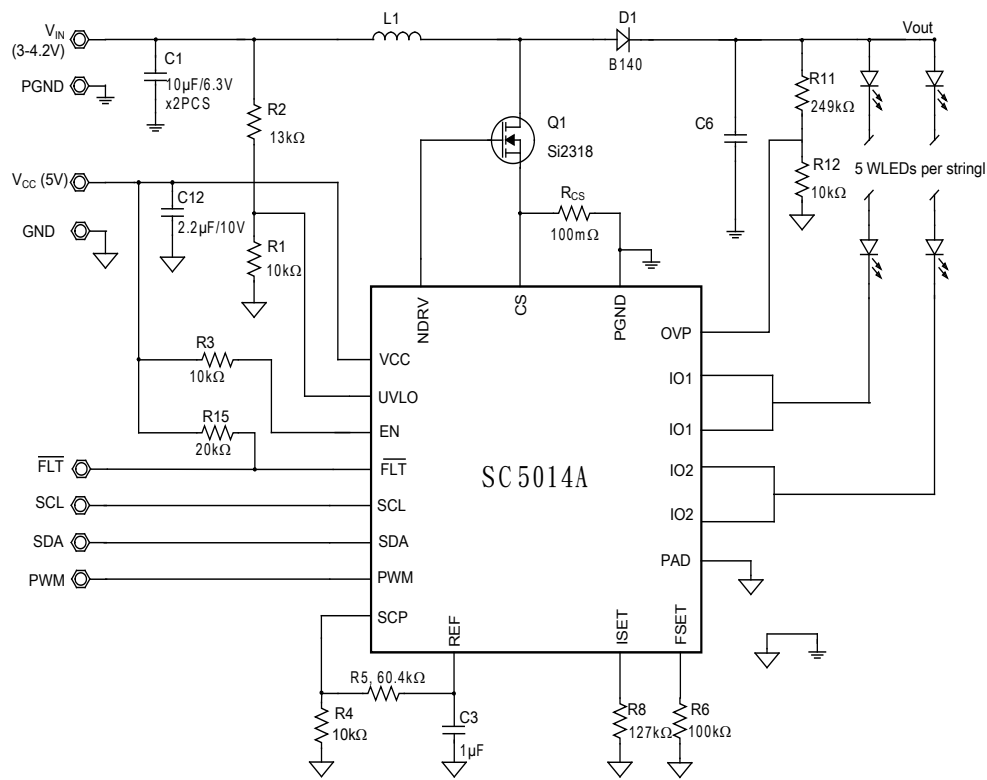


Figure 3— Li-Ion Powered Display Application Circuit Example, 10 LED @ 40mA

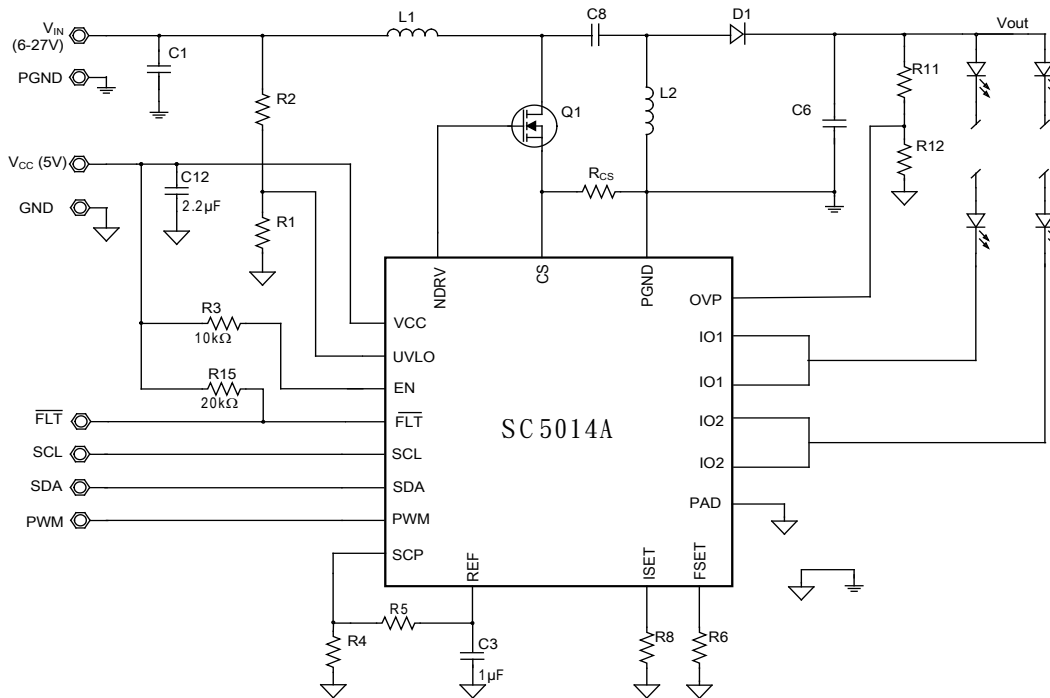


Figure 4—SEPIC Configuration

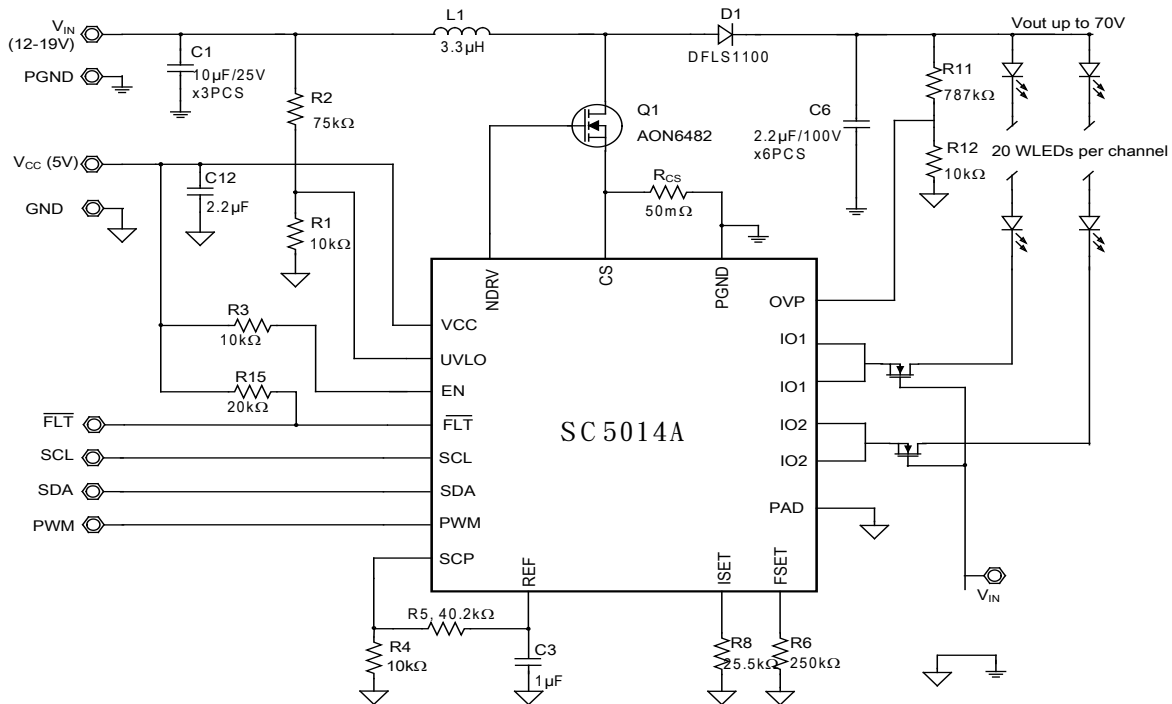


Figure 5—Cascode Configuration drives 40 LEDs@200mA

Serial Interface

The I²C General Specification

The SC5014A is a read-write slave-mode I²C device and complies with the NXP B.V. I²C standard Version 2.1, dated January 2000. The SC5014A has 11 user-accessible internal 8-bit registers. The I²C interface has been designed for program flexibility, supporting direct format for write operation. Read operations are supported on both combined format and stop separated format. While there is no auto increment/decrement capability in the SC5014A I²C logic, a tight software loop can be designed to randomly access the next register independent of which register you begin accessing. The start and stop commands frame the data-packet and the repeat start condition is allowed if necessary.

Limitations to the I²C Specifications

The SC5014A only recognizes 7-bit addressing. This means that 10-bit addressing and CBUS communication are not compatible. The device can operate in either standard mode (100kbit/s) or fast mode (400kbit/s).

Slave Address Assignment

The 7-bit slave address is 0101 111x. The eighth bit is the data direction bit. 0x5F is used for read operation and 0x5E is used for write operation.

Supported Formats

The supported formats are described in the following subsections.

(1) Direct Format — Write

The simplest format for an I²C write is direct format. After the start condition [S], the slave address is sent, followed by an eighth bit indicating a write. The SC5014A I²C then acknowledges that it is being addressed, and the master responds with an 8-bit data byte consisting of the register address. The slave acknowledges and the master sends the appropriate 8-bit data byte. Once again, the slave

acknowledges and the master terminates the transfer with the stop condition [P].

(2) Combined Format — Read

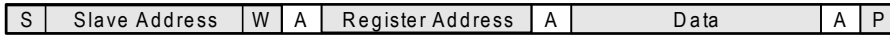
After the start condition [S], the slave address is sent, followed by an eighth bit indicating a write. The SC5014A I²C then acknowledges that it is being addressed, and the master responds with an 8-bit data byte consisting of the register address. The slave acknowledges and the master sends the repeated start condition [Sr]. Once again, the slave address is sent, followed by an eighth bit indicating a read. The slave responds with an acknowledge and the 8-bit data from the previously addressed register; the master then sends a non-acknowledge (NACK). Finally, the master terminates the transfer with the stop condition [P].

(3) Stop Separated Reads

Stop-separated reads can also be used. This format allows a master to set up the register address pointer for a read and return to that slave at a later time to read the data. In this format the slave address followed by a write command are sent after a start [S] condition. The SC5014A then acknowledges it is being addressed, and the master responds with the 8-bit register address. The master sends a stop or restart condition and may then address another slave. After performing other tasks, the master can send a start or restart condition to the SC5014A with a read command. The device acknowledges this request and returns the data from the register location that had previously been set up.



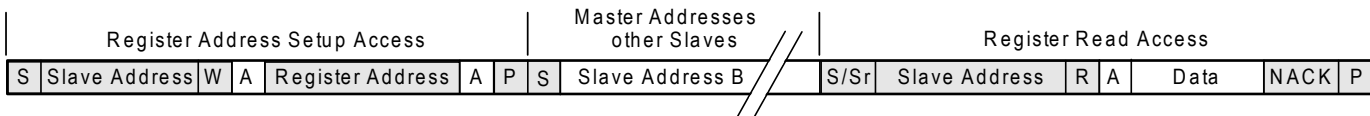
I²C Direct Format Write



S – Start Condition
 W – Write = '0'
 A – Acknowledge (sent by slave)
 P – Stop condition

Slave Address – 7-bit
 Register address – 8-bit
 Data – 8-bit

I²C Stop Separated Format Read



S – Start Condition
 W – Write = '0'
 R – Read = '1'
 A – Acknowledge (sent by slave)
 NAK – Non-Acknowledge (sent by master)
 Sr – Repeated Start condition
 P – Stop condition

Slave Address – 7-bit
 Register address – 8-bit
 Data – 8-bit

I²C Combined Format Read



S – Start Condition
 W – Write = '0'
 R – Read = '1'
 A – Acknowledge (sent by slave)
 NAK – Non-Acknowledge (sent by master)
 Sr – Repeated Start condition
 P – Stop condition

Slave Address – 7-bit
 Register address – 8-bit
 Data – 8-bit

Register Map

Address	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Value	Description
0x00	CLF		LED_SHORT	LED_OPEN		OTP	OVP	FAULT	0x00	Fault Status
0x02				IDAC4	IDAC3	IDAC2	IDAC1	IDAC0	0x1F	Analog Dimming Control

Definition of Registers and Bits

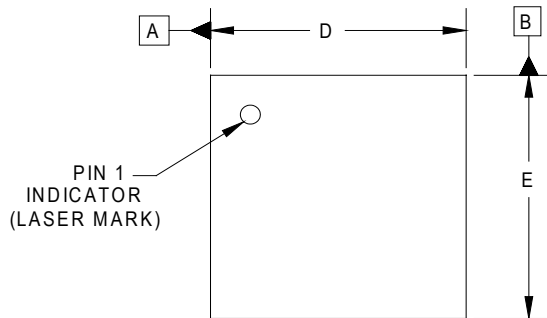
Fault Status Register

Bit Field	Definition	Read / Write	Description
0x00 [7]	CLF	W	Clear latching flags bit. (Set = 1 to clear OTP, LED_OPEN, LED_SHORT and mask OVP for 32 to 64μs)
0x00 [5]	LED_SHORT	R	One or more LED strings faulted shorted
0x00 [4]	LED_OPEN	R	One or more LED strings faulted open
0x00 [2]	OTP	R	Thermal shutdown (1 = thermal OTP fault)
0x00 [1]	OVP	R	Output over-voltage fault (1 = OVP)
0x00 [0]	FAULT	R	OR of all fault conditions (0= no fault, 1 = fault condition)

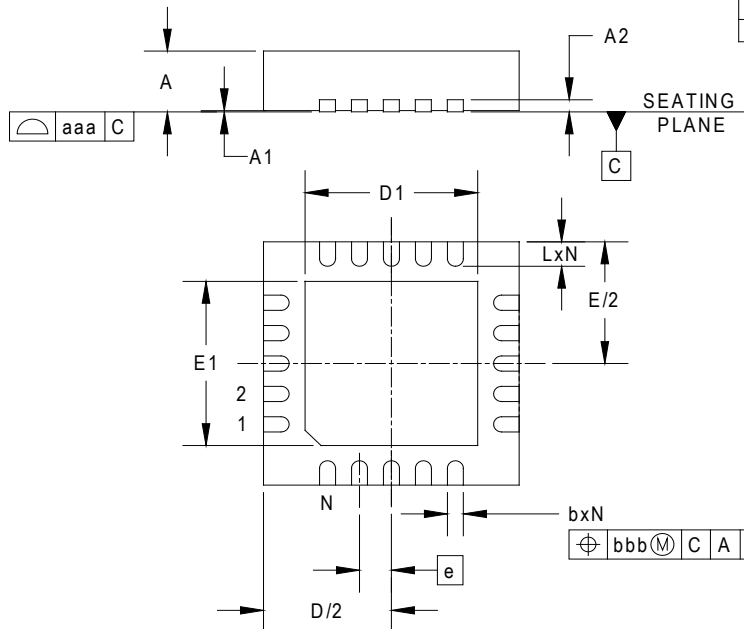
Analog Dimming Control Register

Bit Field	Definition	Read / Write	Description
0x02 [4:0]	IDAC [4:0]	R / W	5-bit analog dimming register — The LED current can adjusted in 32 steps from 0mA to max value determined by R_{ISET}

Outline Drawing — MLPQ-20 4x4

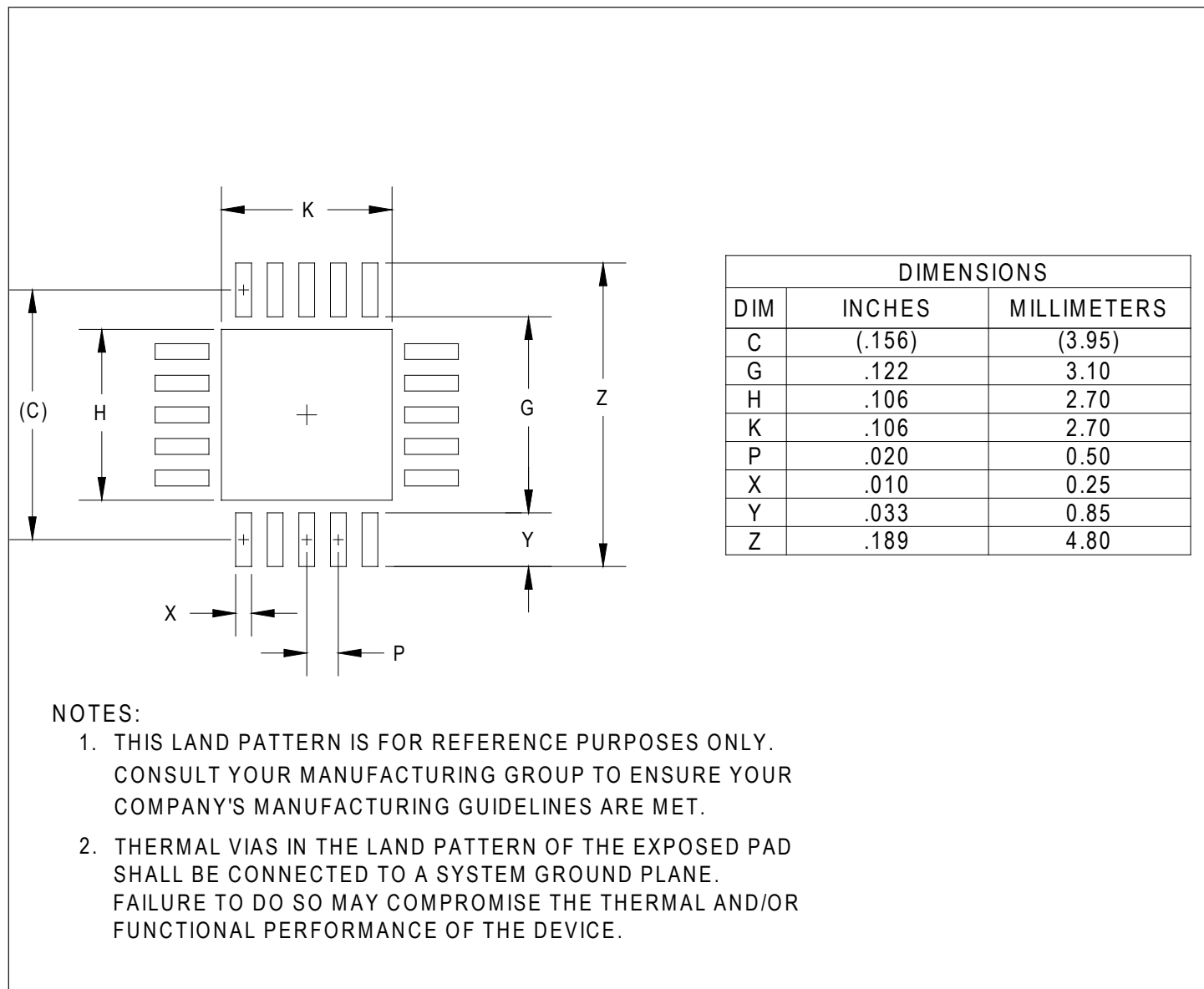


DIM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	.031	.035	.039	0.80	0.90	1.00
A1	.000	.001	.002	0.00	0.02	0.05
A2	-	(.008)	-	-	(0.20)	-
b	.007	.010	.012	0.18	0.25	0.30
D	.154	.157	.161	3.90	4.00	4.10
D1	.100	.106	.110	2.55	2.70	2.80
E	.154	.157	.161	3.90	4.00	4.10
E1	.100	.106	.110	2.55	2.70	2.80
e	.020 BSC			0.50 BSC		
L	.012	.016	.020	0.30	0.40	0.50
N	20			20		
aaa	.004			0.10		
bbb	.004			0.10		



NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

Land Pattern — MLPQ-20 4x4




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